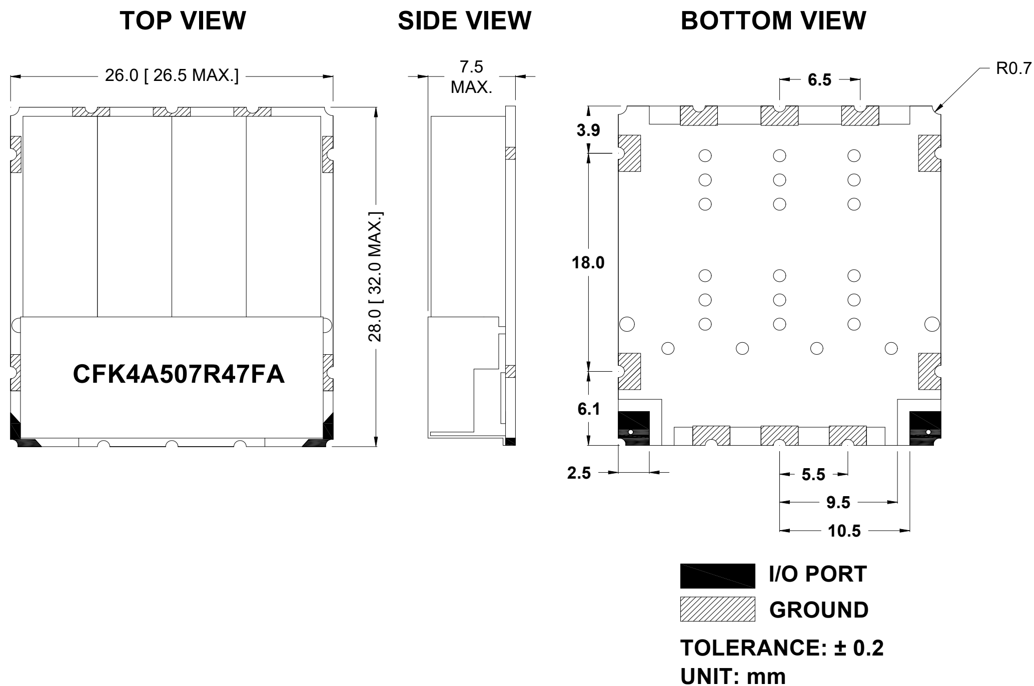
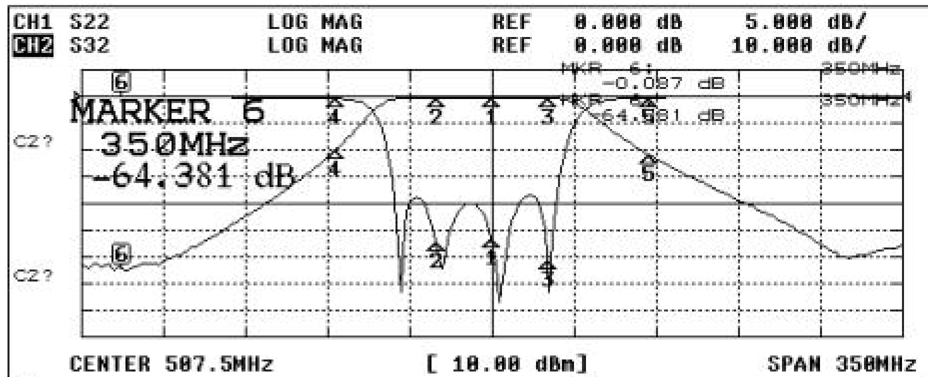
Electrical Specification

ITEMS	SPEC	UNIT
Center Frequency [fo]	507.5	MHz
Bandwidth [BW]	fo ±23.5 [484.0 ~ 531.0]	MHz
Insertion Loss in BW	1.5	dB max
Ripple in BW	0.4	dB max
Return Loss in BW	15.0	dB min
Attenuation ☑ Absolute Value ☐ Relative Value	20.0 dB min @ fo ± [441.0 &]	MHz
	20.0 dB min @ fo ± [574.0 &]	MHz
	60.0 dB min @ fo ± [350.0 &]	MHz
	dB min @ fo ± [&]	MHz
Group Delay Variation	5.0	ns max
Input Power		W max.
In/Out Impedance	50 Ω	
Operation Temperature Range	-40℃ to +85℃	

Mechanical Specification

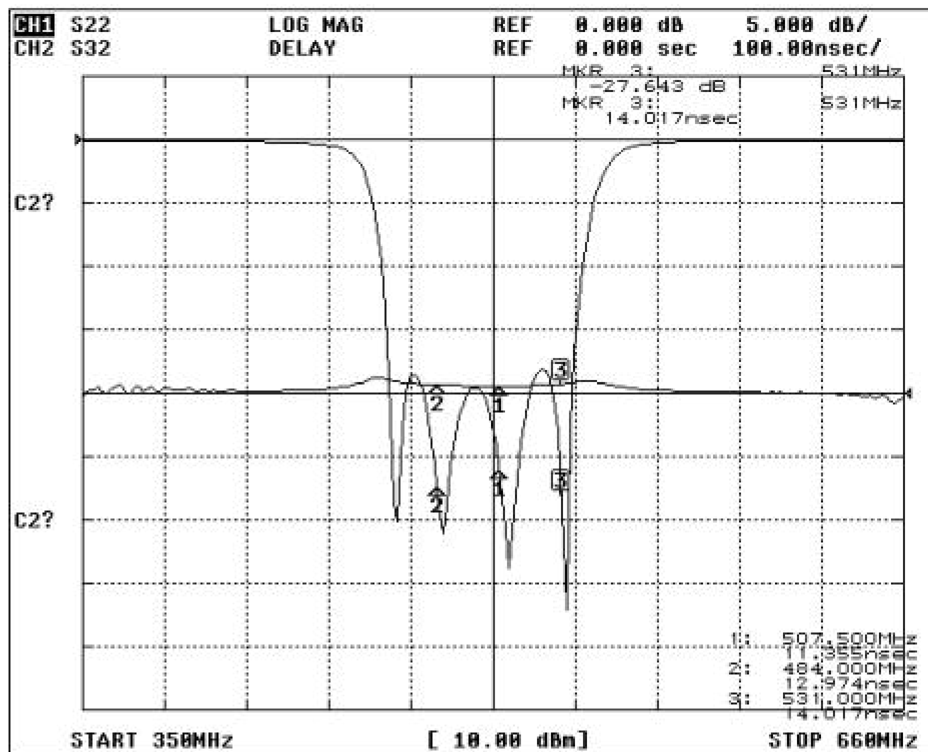


Plot Data

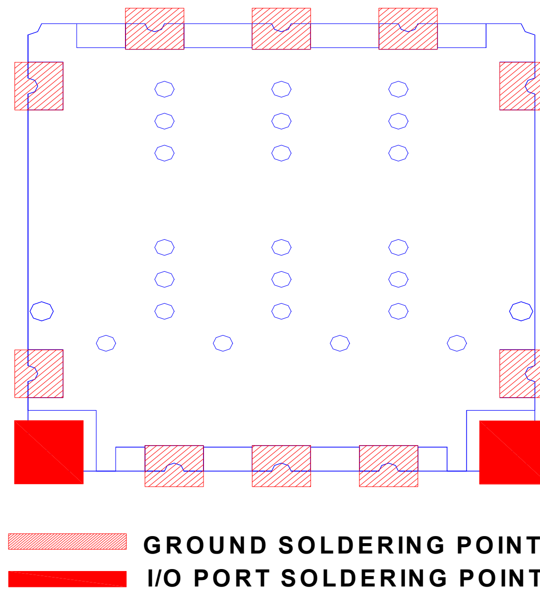


CH2 MARKER LIST

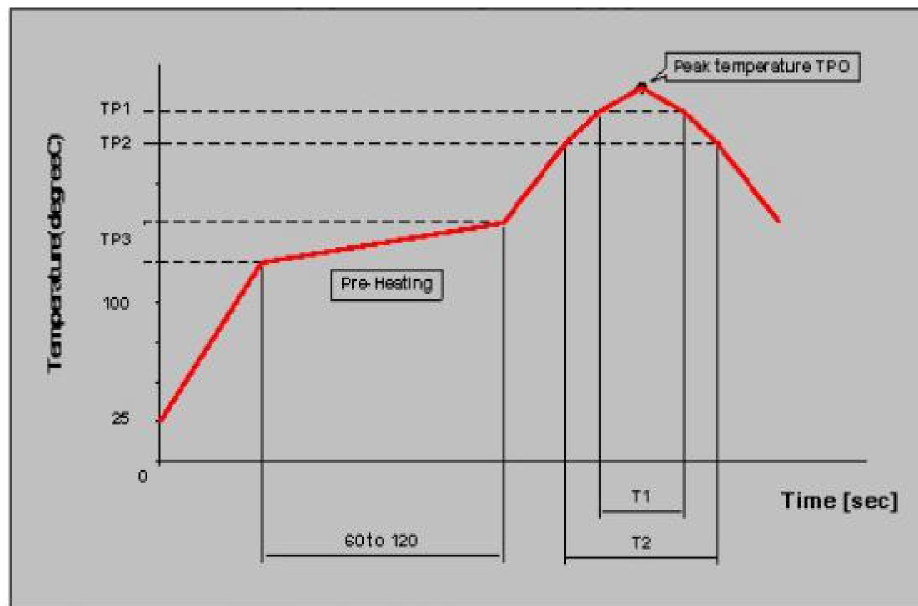
	Frequency	Level
1:	507.500MHz	-0.518 dB
2:	484.000MHz	-0.598 dB
3:	531.000MHz	-0.603 dB
4:	441.000MHz	-20.213 dB
5:	574.000MHz	-21.573 dB
6:	350.000MHz	-64.381 dB
7:		
8:		
9:		
10:		



Recommanded PC Board Pattern



Soldering Condition



Measuring point of temperature : IN-OUT Terminals of The Device

Reflow Soldering : Both Convection and Infrared Rays, Hot Air and Hot Plate

Reflow standard condition	TP0 (℃)	TP1 (℃)	T1 (s)	TP2 (℃)	T2 (s)	TP3 (℃)
Sn-3Ag-0.5 solder	245+/-5	220	30 to 60	—	—	150 to 180
Test condition of reflow heat resistance	260+5/-0	240	20	220	70	150 to 180